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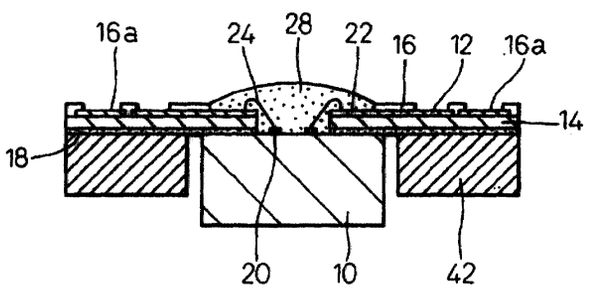
(54) Manufacturing a semiconductor device using a film substrate

(57) Semiconductor devices are manufactured, using film substrates, as follows. Individual film substrates are separated from a film substrate tape (122) having a plurality of film substrates continuously and integrally connected to each other, each the film substrate comprising a base film (14) having first and second surfaces, a circuit pattern (16) being formed in the first surface and a mounting section being formed on the second surface. The base film (14) has an opening (15) to which electrode terminals (20) of a semiconductor element (10) are exposed when the semiconductor element (10) is mounted. The individual film substrates are adhered to respective reinforcement members (32, 42) of a reinforcement frame (40), which has a plurality of the reinforcement members continuously and integrally connected to each other. Each reinforcement member (32, 42) has an accommodation hole (44) for accommodating the semiconductor element (10), so that the semiconductor element mount section is exposed in the accommodation hole (40). A semiconductor element (10) is mounted on the film substrate by adhering an electrode terminal-forming surface of the semiconductor element (10) to said mounting section so that electrode terminals (20) of the semiconductor element are exposed in the accommodation hole (40). The electrode terminals (20) exposed in the opening (15) are electrically connected to the circuit patterns (16). The opening (15) is sealed with resin (28) and then the individual reinforcement members (32, 42) are separated from the reinforcement frame.

Fig.6



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EUROPEAN SEARCH REPORT

Application Number
EP 99 30 7877

DOCUMENTS CONSIDERED TO BE RELEVANT

Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (Int.Cl.7)
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A	US 5 767 528 A (SUMI YUKINORI ET AL) 16 June 1998 (1998-06-16) * abstract; figures 3-5 *	1-9	
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TECHNICAL FIELDS SEARCHED (Int.Cl.7)

H01L

The present search report has been drawn up for all claims

Place of search	Date of completion of the search	Examiner
BERLIN	1 August 2001	Munnix, S

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